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TRANSMITTAL LETTER
(General - Patent Pending)

Docket No.
11675.76.3

In Re Application Of: Sandhu, et al.

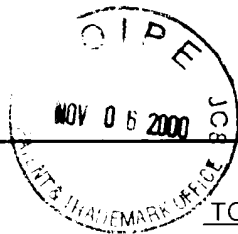
Serial No.
09/627,649

Filing Date
July 28, 2000

Examiner
Not yet assigned

Group Art Unit
2811

Title: INTERLEVEL DIELECTRIC STRUCTURE



TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is:

Transmittal Letter (1 pg. in duplicate);
Transmittal of Information Disclosure Statement (2 pgs. in duplicate);
Information Disclosure Citation (2 pgs.);
Information Disclosure Statement (3 pgs.);
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in the above identified application.

- ☒ No additional fee is required.
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- ☒ The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. **23-3178** as described below. A duplicate copy of this sheet is enclosed.
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Bradley K. DeSandro
Reg. No. 34,521

Dated: November ¹⁵ 2000



022901

U.S. PATENT AND TRADEMARK OFFICE

I certify that this document and fee is being deposited on Nov. 15, 2000 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C.

Signature of Person Mailing Correspondence

Bradley K. DeSandro

Typed or Printed Name of Person Mailing Correspondence

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
11675.76.3

In Re Application Of:
Sandhu, et al.

Serial No.
09/627,649

Filing Date
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Group Art Unit
2811

Title: INTERLEVED DIELECTRIC STRUCTURE



Address to:
Assistant Commissioner for Patents
Washington, D.C. 20231

37 CFR 1.97(b)

1. ☒ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application; within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or before the mailing date of a first Office Action on the merits, whichever event occurs last.

37 CFR 1.97(c)

2. ☐ The Information Disclosure Statement submitted herewith is being filed after three months of the filing of a national application, or the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; or after the mailing date of a first Office Action on the merits, whichever occurred last but before the mailing date of either:

1. a Final Action under 37 CFR 1.113, or
 2. a Notice of Allowance under 37 CFR 1.311,
- whichever occurs first.

Also submitted herewith is:

- ☐ a certification as specified in 37 CFR 1.97(e);

OR

- ☐ the fee set forth in 37 CFR 1.17(p) for submission of an Information Disclosure Statement under 37 CFR 1.97(c).

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TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 1.97(b) or 1.97(c))

Docket No.
11675.76.3

In Re Application Of:
Sandhu, et al.

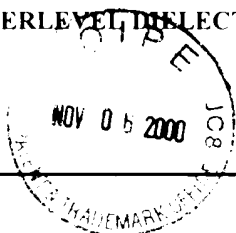
Serial No.
09/627,649

Filing Date
July 28, 2000

Examiner
Not yet assigned

Group Art Unit
2811

Title: INTERLEVEL DIELECTRIC STRUCTURE



Payment of Fee

(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

- ☐ A check in the amount of _____ is attached.
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Bradley K. DeSandro

Typed or Printed Name of Person Mailing Correspondence

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Signature

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Reg. No. 34,521

Dated: November ¹⁵, 2000



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sandhu, et al.

Serial No.: 09/627,649

Filed: July 28, 2000

For: INTERLEVEL DIELECTRIC STRUCTURE

Examiner: Not yet assigned

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INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. § 1.97

Assistant Commissioner for Patents
Washington, D.C. 20231

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Sir:

Please find, pursuant to 37 C.F.R. § 1.98(a)(1), the enclosed Form PTO-1449 which contains a list of all patents, publications, or other items that have come to the attention of one or more of the individuals designated in 37 C.F.R. § 1.56(c). While no representation is made that any of these references may be "prior art" within the meaning of that term under 35 U.S.C. §§ 102 or 103, the enclosed list of references is disclosed so as to fully comply with the duty of disclosure set forth in 37 C.F.R. § 1.56.

Moreover, while no representation is made that a specific search of office files or patent office records has been conducted or that no better art exists, the undersigned attorney

invention (taken in its entirety) has been knowingly withheld.

Statement of References Previously Disclosed
Under 37 C.F.R. § 1.98(d)

The following listed references are not enclosed because, under 37 C.F.R. § 1.98(d), they were previously cited by or submitted to the Office in application number 08.677,514, filed on July 10, 1996, which is relied upon for an earlier filing date under 35 U.S.C. § 120.

United States Patent Documents

<u>Patent Number</u>	<u>Issue Date</u>	<u>Name</u>	<u>Class</u>	<u>Sub Class</u>	<u>Filing Date</u>
5,445,996	8/95	Kodera et al.	438	633	
5,486,493	1/96	Jeng	438	623	
5,399,235	3/95	Mutsaers et al.	438	633	
5,420,075	5/95	Homma et al.	438	624	
5,599,740	2/97	Jang et al.	438	626	
5,677,239	10/97	Isobe	438	633	
5,795,829	8/98	Shen	438	694	
5,708,303	1/98	Jeng	257	758	

Other Documents

M.K. Jain et al., "Advanced Metalization and Interconnect systems for ULSI Applications: Homogenous and Multilayer Low-K Interlevel Dielectric Architectures for Capacitance Reduction," Conference at University of California, Berkeley, California, October 1996.

Tetsuya Homma, "Fluorinated SiO₂ Films for Interlayer Dielectrics in Quarter-Micron ULSI Multilevel Interconnections," Mat. Res. Soc. Symp. Proc., vol. 381, pp. 239-248, 1995.

J. Wary et al., "Vacuum-Deposited Parylene AF-4: A Thermally Stable, Low Dielectric Constant Polymer For Interlayer Dielectric Use," DUMIC Conference, pp. 207-213, February, 1996.

Dated this 28 day of October, 2000.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'Bradley K. Desandro', is written over a horizontal line.

BRADLEY K. DESANDRO
Attorney for Applicant
Registration No. 34,521

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